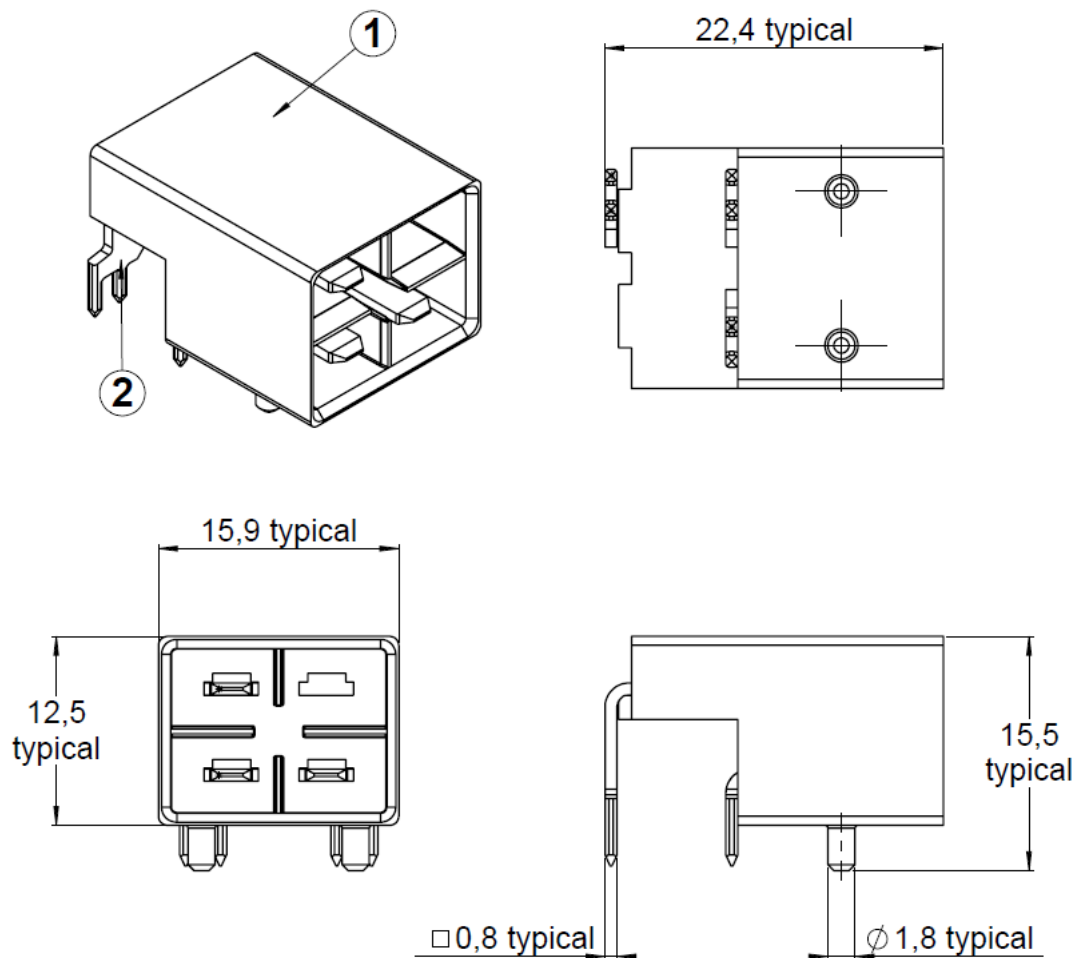


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All dimensions are in mm. Tolerances according ISO 2768 m-H

DESCRIPTION

REP	COMPONENT	MATERIALS	PLATING
1	Housing	PLASTIC	-
2	Contact	COPPER ALLOY	SN

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GENERAL CHARACTERISTICS

Mechanical Mating endurance (cycles) Vibration Weight (g)	EIA 364-09 IEC 60068-2-6 -	100 10-150-10 Hz 3.551
Environmental Operating temperature (°C) Storage temperature (°C) RoHS Flammability	- - - UL 94	-40 / +105 -65 / +105 Compliant V0
Electrical Working voltage Current rating Dielectric withstanding voltage Insulation resistance	- - EIA 364-20 EIA 364-21	Max. 300V AC or DC (r.m.s.) 30A per contact 500V DC 5000MΩ minimum initial 1000MΩ minimum after environmental aging
Others Packaging	-	Packaging in Tape & Reel, 150 per reel

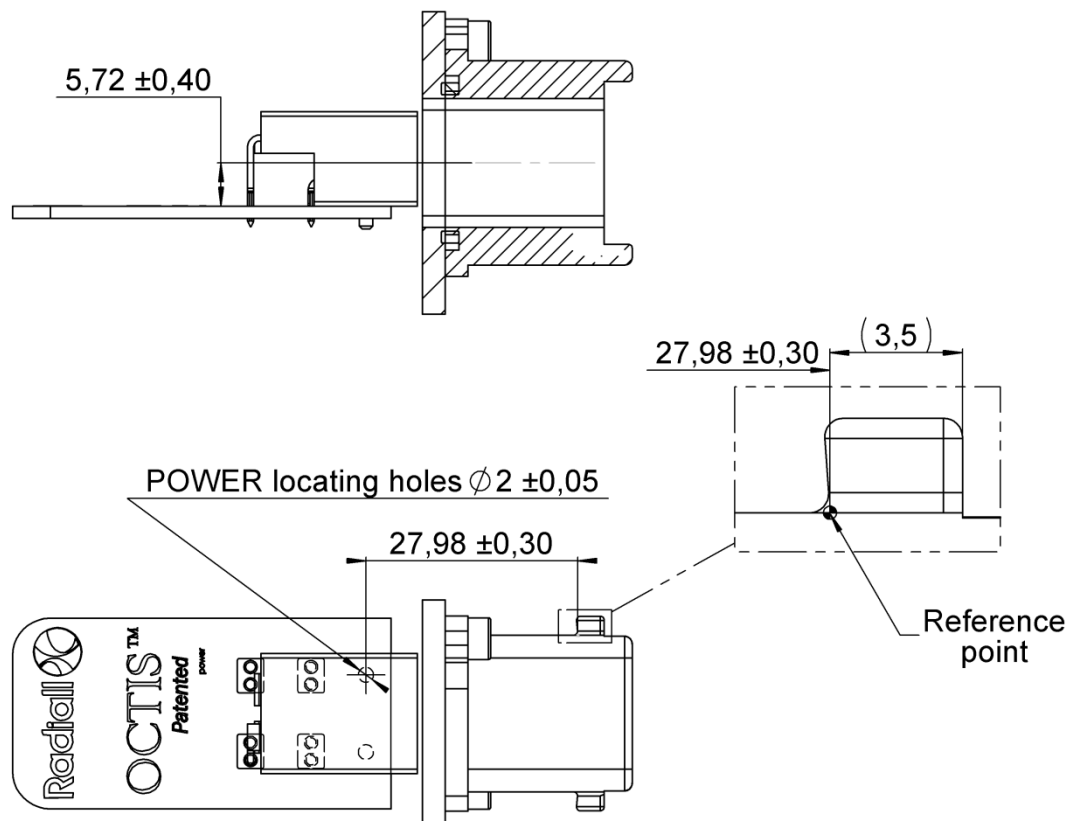
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POSITIONING AND PATTERN DEFINITION



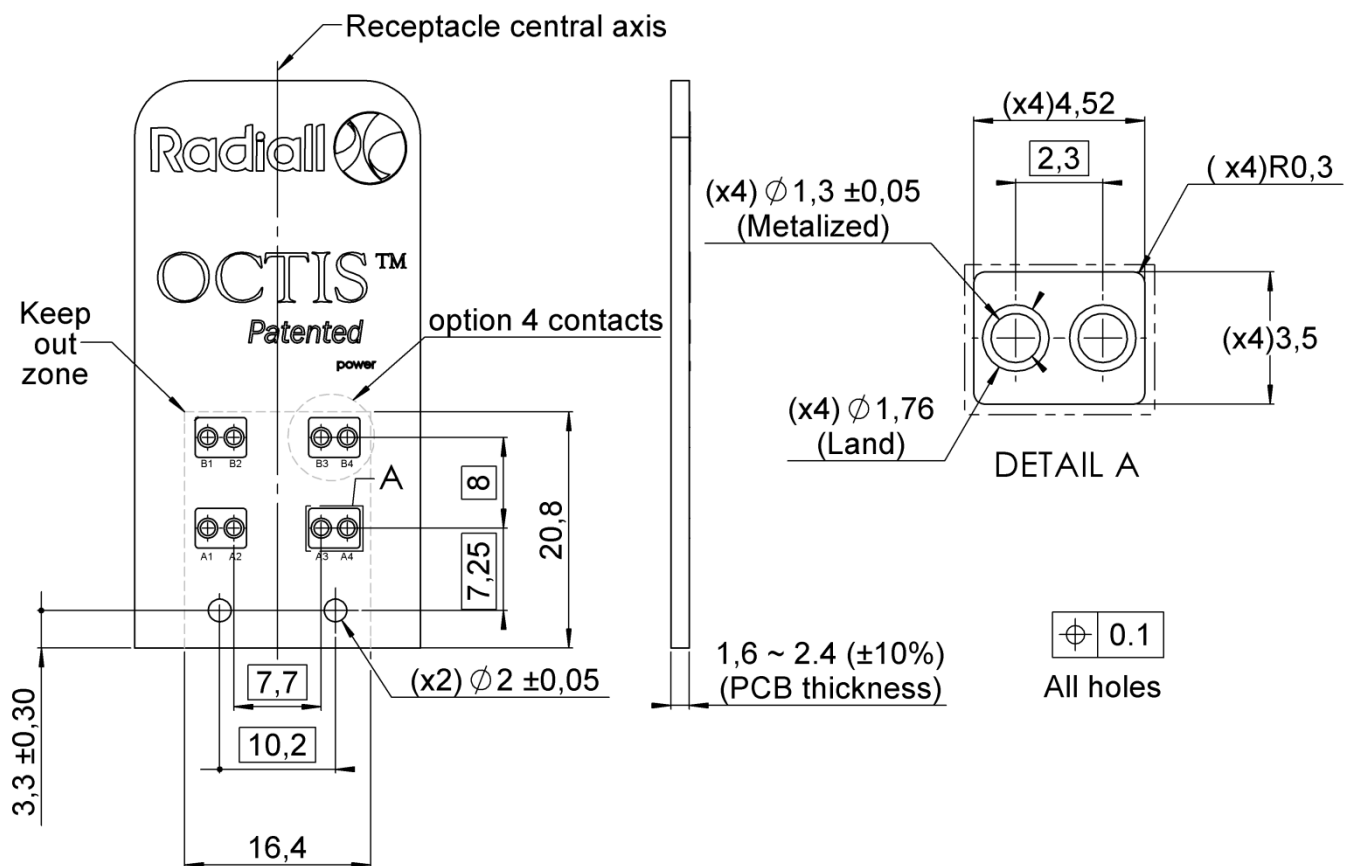
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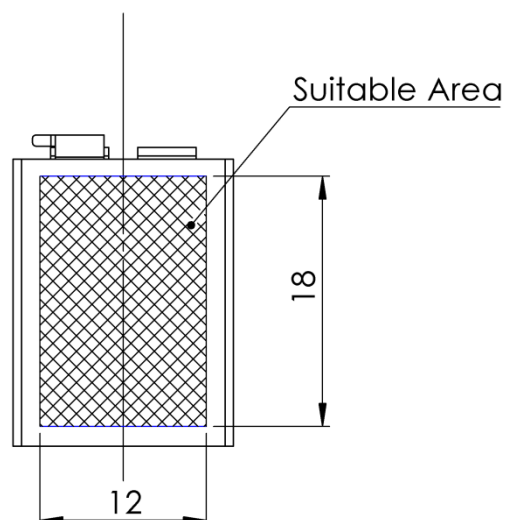
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FOOT/PRINT (General tolerance for PCB ± 0.1 mm)



SUITABLE AREA FOR PICK & PLACE VACUUM NOZZLE



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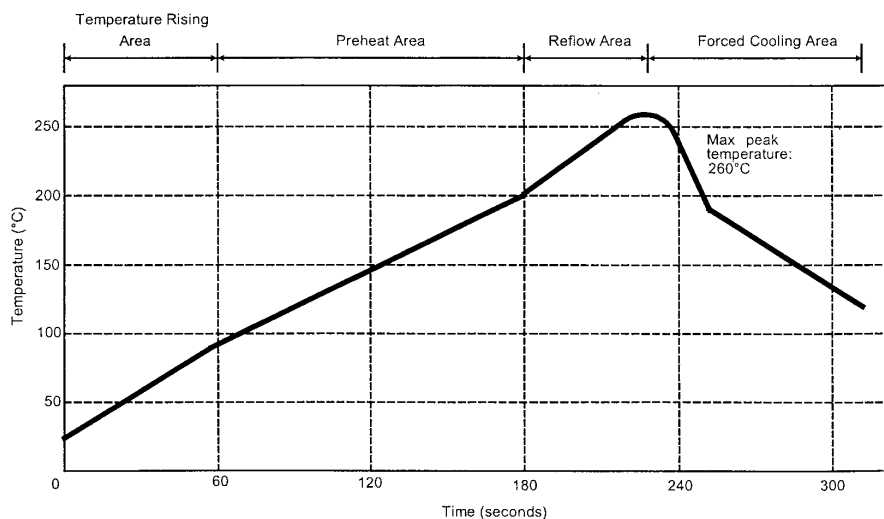
PART NUMBER OCTI363500

SOLDER PROCEDURE*

1. Deposit solder paste (Sn Ag4 Cu0.5) on solder pads / mounting area by screen printing application. We recommend a low residue flux. Verify that the edges of the pads are clean.
2. Place the component on the mounting area with a pick & place machine. A video camera is recommended for a good positioning of the component. Adhesive agents must not be used on the component.
3. This process of soldering has been tested with a convection oven. Below please find the typical soldering profile to use.
4. Optional cleaning of printed circuit board.
5. Check solder joints and position of the component by visual inspection.

Note: When soldering a receptacle, no plug should be mated to the receptacle before completion of this procedure.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 to 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

* Typical data for reflow process. Alternatively, wave soldering is also possible